

10/537539
JC06 Rec'd 07/PTO 03 JUN 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent Application
Bernard Paul Joseph THIERS

Examiner: Unassigned

DO/EO/US

Serial Number: Unassigned

Filed: Herewith

Attorney Docket No.: THIE3020/JEK

For: FLOOR PANEL, ITS LAYING AND MANUFACTURING METHODS

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to Rule 37 C.F.R. §1.51(b), §1.56, §1.97, and §1.98, this Information Disclosure Statement is submitted in the above-identified patent application. A listing of documents to be published on the face of any patent granted from this application is submitted herewith on Form PTO-1449. Any other documents or information submitted for consideration by the Examiner are listed in this paper. A copy of each foreign patent, or each publication or portion thereof listed or herein identified is submitted herewith.

ADDITIONAL DOCUMENTS OR INFORMATION NOT LISTED ON
ACCOMPANYING FORM PTO-1449 SUBMITTED FOR CONSIDERATION

International Search Report dated May 25, 2004 issued in International Patent Application No. PCT/EP03/14548 of which this application is the U.S. national stage.

CONCISE STATEMENT OF RELEVANCY
(NON-ENGLISH LANGUAGE DOCUMENTS ONLY)

All of the documents identified on the appended PTO-1449 form are identified in the International Search Report established in PCT/EP03/14548, of which this application is the U.S. national stage. The relevancy of the documents is evident from the Search Report.

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STATEMENT OF CUMULATIVE INFORMATION

U.S. published patent application No. U.S. 2003/101674A1 corresponds to WO 03/025307.

U.S. published patent application No. U.S. 2003/205017A1 corresponds to DE 20207021.

STATEMENT REGARDING TRANSLATIONS

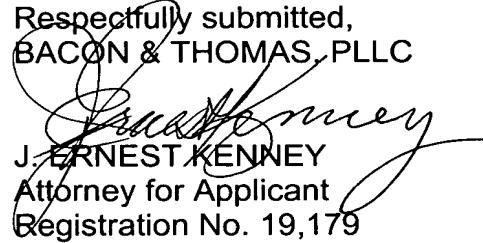
A translation the non-English language documents is not readily available to Applicants' attorney.

The translation appearing in the patent abstracts of Japan document is the only translation available of this Japanese document to Applicants' attorney.

STATEMENT OF TIMELINESS

This Information Disclosure Statement is submitted within three months of (i) the filing date of the above-identified U.S. National Patent application, or (ii) the date of entry into the U.S. National Stage of the above-identified International Application, or (iii) the date of entry into the U.S. National Stage of the International Application that has been assigned the above-identified U.S. Patent application number, whichever applies.

The Examiner is requested to acknowledge consideration of the information provided in this paper in accordance with prescribed procedures.

Respectfully submitted,
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B/O Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office Information Disclosure Statement by Applicant		Atty. Docket Number THIE3020/JEK	Serial Number 10/1537539 Unassigned
		Applicant Bernard Paul Joseph THIERS	
		Filing Date Herewith	Group Unassigned

U.S. Patent Documents

Examiner Initial		Document Number	Date	Patentee/Applicant	Class	Subclass	Filing Date if Appropriate
		1,787,027	Dec. 1930	Wasleff			
		2,015,813	Oct. 1935	Nielsen Herman C.			
		5,117,603	Jun. 1992	Weintraub Fred I.			

Foreign Patent Documents

Examiner Initial		Document Number	Publication Date	Country/Agency	Class	Subclass	Translation	
							Yes	No
		202 07 021 U	Sep. 2002	Germany				X
		03/025307 A	Mar. 2003	WIPO				

Other Documents (Including Author, Title, Date, Pertinent Pages, Place of Publication, Etc.)

		Patent Abstracts of Japan, Pub. No. 05214802A, published 24.08.1003, Tosutemu Utsudo Waaku KK.

Examiner	Date Considered

EXAMINER: Initial if citation is considered, whether or not citation is in conformance with MPEP 609; Draw a line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.